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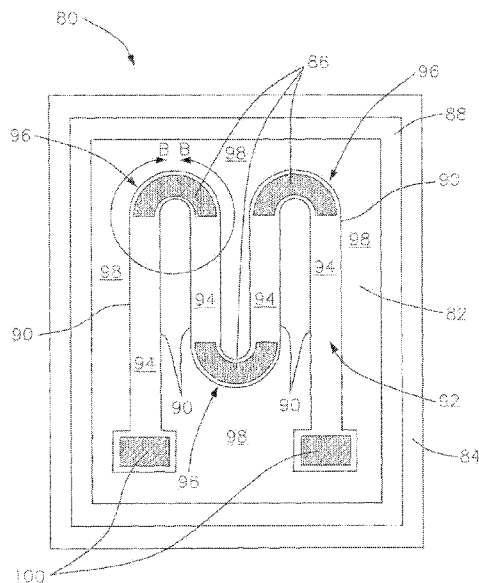
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(54) Title: LAYERED HEATER SYSTEM HAVING CONDUCTIVE OVERLAYS



(57) Abstract: A layered heater (20) includes a resistive layer (26) defining a resistive circuit pattern having at least one bend portion (32). A conductive overlay (36) is provided on at least one of a top surface (38) and a bottom surface (40) of the bend portion (32) to alleviate the current crowding effect, thereby protecting the electric circuit from premature failure. Methods of manufacturing the layered heater are also disclosed. The overlay may be formed on the bend portion after the resistive layer is formed. The overlay may also be formed on a substrate or a dielectric layer that supports the resistive layer before the resistive layer is formed.

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